# Introduction to CMOS VLSI Design

# Lecture 17: Design for Testability

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Harvey Mudd College Spring 2004

#### Outline

- □ Testing
  - Logic Verification
  - Silicon Debug
  - Manufacturing Test
- □ Fault Models
- Observability and Controllability
- Design for Test
  - Scan
  - BIST
- □ Boundary Scan

# Testing

- ☐ Testing is one of the most expensive parts of chips
  - Logic verification accounts for > 50% of design effort for many chips
  - Debug time after fabrication has enormous opportunity cost
  - Shipping defective parts can sink a company
- Example: Intel FDIV bug
  - Logic error not caught until > 1M units shipped
  - Recall cost \$450M (!!!)

# Logic Verification

- Does the chip simulate correctly?
  - Usually done at HDL level
  - Verification engineers write test bench for HDL
    - Can't test all cases
    - Look for corner cases
    - Try to break logic design
- ☐ Ex: 32-bit adder
  - Test all combinations of corner cases as inputs:
    - 0, 1, 2, 2<sup>31</sup>-1, -1, -2<sup>31</sup>, a few random numbers
- ☐ Good tests require ingenuity

# Silicon Debug

- ☐ Test the first chips back from fabrication
  - If you are lucky, they work the first time
  - If not...
- ☐ Logic bugs vs. electrical failures
  - Most chip failures are logic bugs from inadequate simulation
  - Some are electrical failures
    - Crosstalk
    - Dynamic nodes: leakage, charge sharing
    - Ratio failures
  - A few are tool or methodology failures (e.g. DRC)
- ☐ Fix the bugs and fabricate a corrected chip

#### Shmoo Plots

- ☐ How to diagnose failures?
  - Hard to access chips
    - Picoprobes
    - Electron beam
    - Laser voltage probing
    - Built-in self-test
- ☐ Shmoo plots
  - Vary voltage, frequency
  - Look for cause of electrical failures

Clock period in ns on the left, frequency increases going up Voltage on the bottom, increase left to right

\* indicates a failure

Works at high but not low frequency

Fails at a specific point in the shmoo

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Leakage

Fails at a specific point in the shmoo

Coupling

# Manufacturing Test

- ☐ A speck of dust on a wafer is sufficient to kill chip
- ☐ *Yield* of any chip is < 100%
  - Must test chips after manufacturing before delivery to customers to only ship good parts
- Manufacturing testers are very expensive
  - Minimize time on tester
  - Careful selection of test vectors



# Testing Your Chips

- ☐ If you don't have a multimillion dollar tester:
  - Build a breadboard with LED's and switches
  - Hook up a logic analyzer and pattern generator
  - Or use a low-cost functional chip tester

#### TestosterICs

- ☐ Ex: TestosterICs functional chip tester
  - Designed by clinic teams and David Diaz at HMC
  - Reads your IRSIM test vectors, applies them to your chip, and reports assertion failures

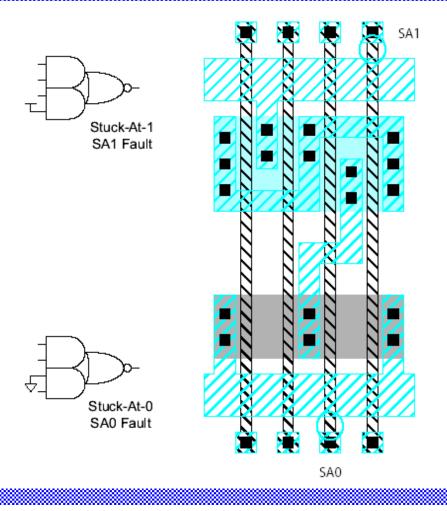




#### Stuck-At Faults

- ☐ How does a chip fail?
  - Usually failures are shorts between two conductors or opens in a conductor
  - This can cause very complicated behavior
- ☐ A simpler model: *Stuck-At* 
  - Assume all failures cause nodes to be "stuck-at"
     0 or 1, i.e. shorted to GND or V<sub>DD</sub>
  - Not quite true, but works well in practice

# Examples



17: Design for Testability

**CMOS VLSI Design** 

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#### Observability & Controllability

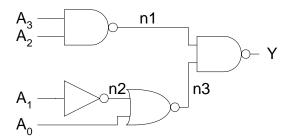
- Observability: ease of observing a node by watching external output pins of the chip
- □ Controllability: ease of forcing a node to 0 or 1 by driving input pins of the chip
- □ Combinational logic is usually easy to observe and control
- ☐ Finite state machines can be very difficult, requiring many cycles to enter desired state
  - Especially if state transition diagram is not known to the test engineer

#### Test Pattern Generation

- Manufacturing test ideally would check every node in the circuit to prove it is not stuck.
- □ Apply the smallest sequence of test vectors necessary to prove each node is not stuck.
- □ Good observability and controllability reduces number of test vectors required for manufacturing test.
  - Reduces the cost of testing
  - Motivates design-for-test

SA1

SA0



Π Δ.

 $\Box$   $A_1$ 

 $\Box$   $A_0$ 

□ n1

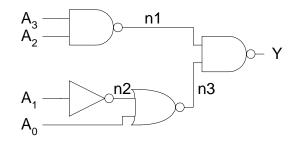
□ n2

**□** n3

■ Minimum set:

 $\Box$   $A_3$ 

SA1 {0110} SA0 {1110}



 $\Box$   $A_1$ 

 $\Box$   $A_0$ 

□ n1

□ n2

**□** n3

■ Minimum set:

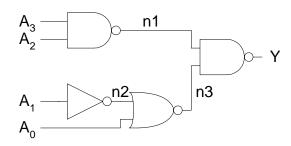
 $\Box$   $A_3$ 

 $A_3 = \{0110\}$  $A_2 = \{1010\}$ 

SA1

SA0 {1110}

{1110}



 $\Box$   $A_0$ 

□ n1

□ n2

□ n3

■ Minimum set:

 $\Box$   $A_3$ 

SA1 {0110} {1010}

{0100}

SA0 {1110} {1110}

{0110}

 $A_3$   $A_2$  n1 n3 n3

 $\Box$   $A_1$ 

 $\Box$   $A_0$ 

□ n1

□ n2

□ n3

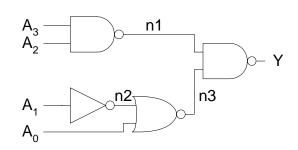
☐ Minimum set:

{0110} {1010} {0100} {0110}

SA1

SA0 {1110} {1110}

> {0110} {0111}



n2

n1

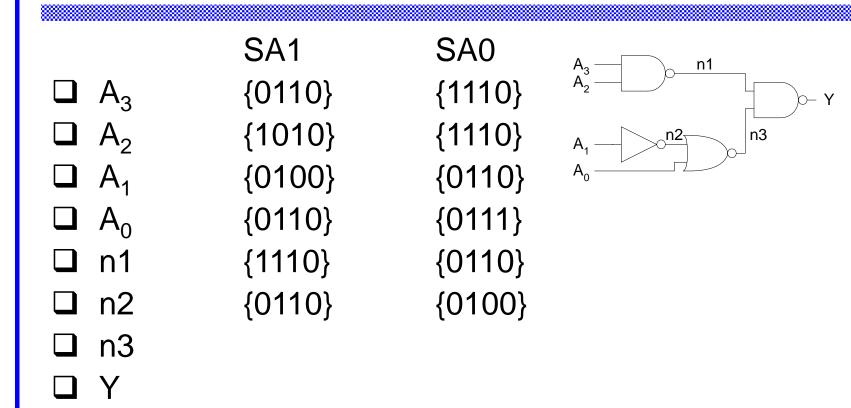
n3

Minimum set:

SA1 SA0 n1 {0110} {1110} {1010} {1110} n3 {0110} {0100} {0110} {0111} {0110} {1110} n1 n2

☐ Minimum set:

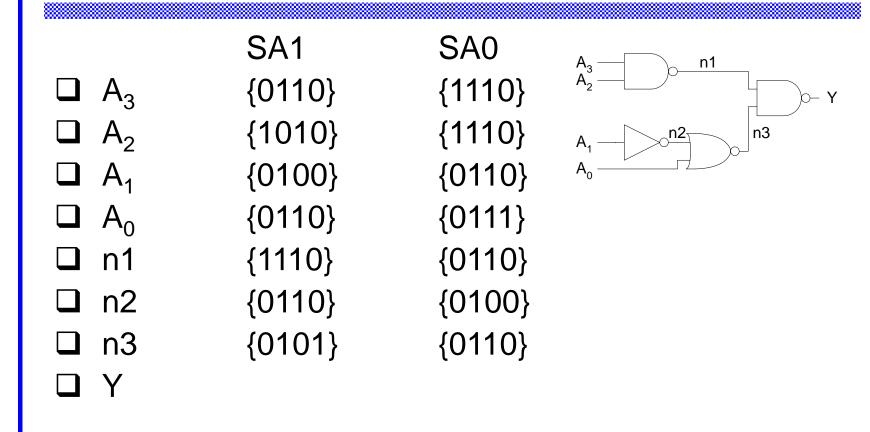
n3



☐ Minimum set:

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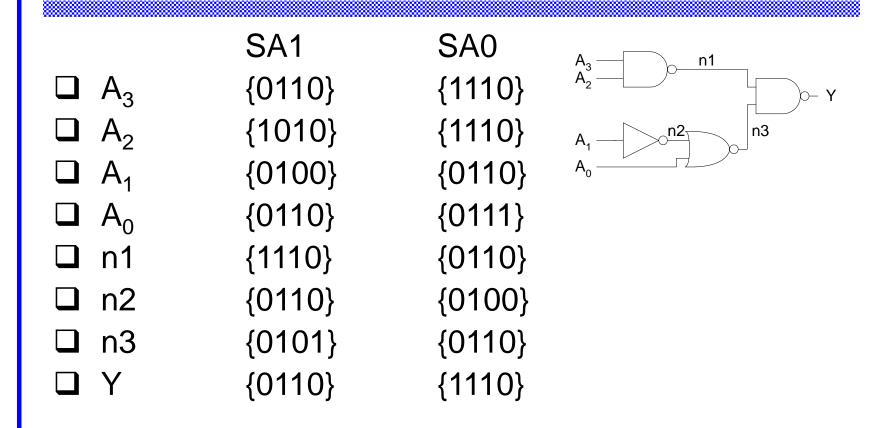
**CMOS VLSI Design** 



☐ Minimum set:

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**CMOS VLSI Design** 



☐ Minimum set: {0100, 0101, 0110, 0111, 1010, 1110}

17: Design for Testability

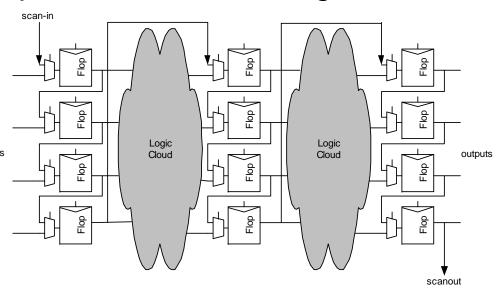
**CMOS VLSI Design** 

# Design for Test

- Design the chip to increase observability and controllability
- ☐ If each register could be observed and controlled, test problem reduces to testing combinational logic between registers.
- □ Better yet, logic blocks could enter test mode where they generate test patterns and report the results automatically.

#### Scan

- ☐ Convert each flip-flop to a scan register
  - Only costs one extra multiplexer
- Normal mode: flip-flops behave as usual
- ☐ Scan mode: flip-flops behave as shift register
- ☐ Contents of flops
  can be scanned
  out and new
  values scanned
  in

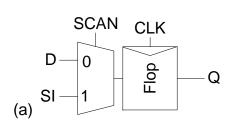


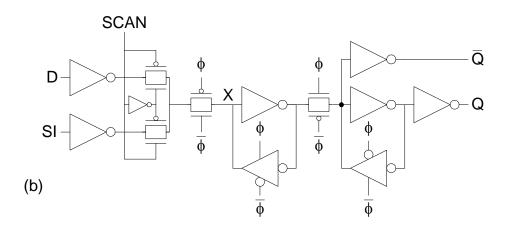
CLK

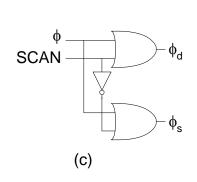
SCAN

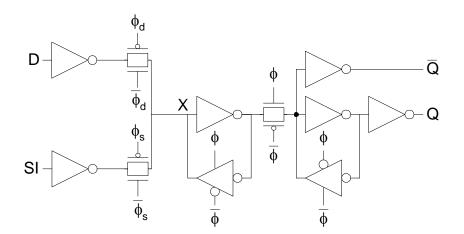
SI ·

# Scannable Flip-flops









17: Design for Testability

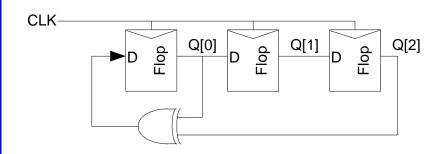
**CMOS VLSI Design** 

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#### Built-in Self-test

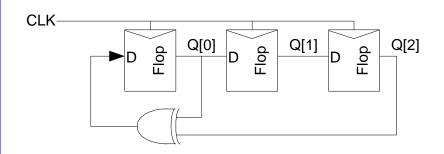
- Built-in self-test lets blocks test themselves
  - Generate pseudo-random inputs to comb. logic
  - Combine outputs into a syndrome
  - With high probability, block is fault-free if it produces the expected syndrome

- ☐ Linear Feedback Shift Register
  - Shift register with input taken from XOR of state
  - Pseudo-Random Sequence Generator



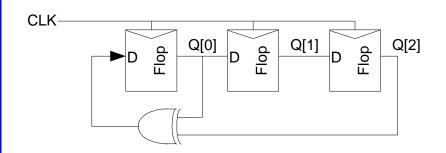
Step	Q
0	111
1	
2	
3	
4	
5	
6	
7	

- ☐ Linear Feedback Shift Register
  - Shift register with input taken from XOR of state
  - Pseudo-Random Sequence Generator



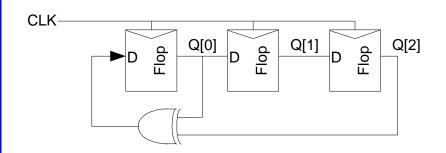
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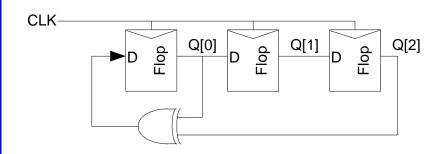
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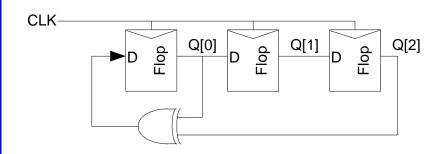
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0	111
1	110
2	101
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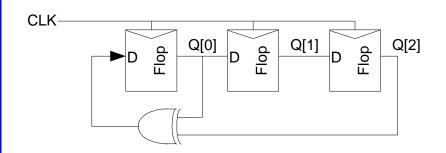
Step	Q
0	111
1	110
2	101
3	010
4	100
5	
6	
7	

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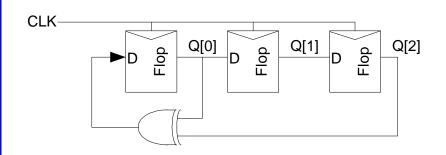
Step	Q
0	111
1	110
2	101
3	010
4	100
5	001
6	
7	

- ☐ Linear Feedback Shift Register
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  - Pseudo-Random Sequence Generator



Step	Q
0	111
1	110
2	101
3	010
4	100
5	001
6	011
7	

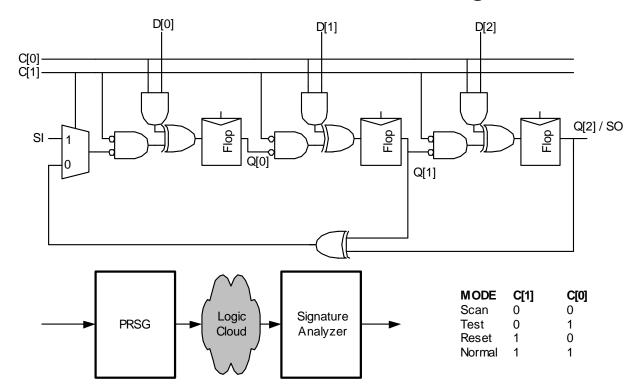
- ☐ Linear Feedback Shift Register
  - Shift register with input taken from XOR of state
  - Pseudo-Random Sequence Generator



Step	Q
0	111
1	110
2	101
3	010
4	100
5	001
6	011
7	111 (repeats)

#### **BILBO**

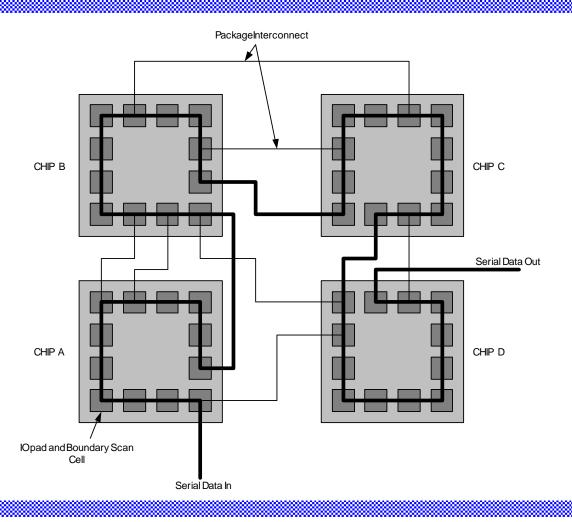
- □ Built-in Logic Block Observer
  - Combine scan with PRSG & signature analysis



# Boundary Scan

- ☐ Testing boards is also difficult
  - Need to verify solder joints are good
    - Drive a pin to 0, then to 1
    - Check that all connected pins get the values
- ☐ Through-hold boards used "bed of nails"
- ☐ SMT and BGA boards cannot easily contact pins
- Build capability of observing and controlling pins into each chip to make board test easier

# Boundary Scan Example



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# Boundary Scan Interface

□ Boundary scan is accessed through five pins

– TCK: test clock

– TMS: test mode select

– TDI: test data in

– TDO: test data out

– TRST\*: test reset (optional)

☐ Chips with internal scan chains can access the chains through boundary scan for unified test strategy.

# Summary

- Think about testing from the beginning
  - Simulate as you go
  - Plan for test after fabrication
- "If you don't test it, it won't work! (Guaranteed)"